Board Characteristics - 6 LAYER BOARD

1. Tg > 170°C
2. Minimum trace width: 0.005" and clearance: 0.005"
3. 1 oz copper for all layers
4. Electroless Nickel Immersion Gold plating, with min. Ni: 2.5-5 um; Au: 0.05-0.2 um.
5. Board Thickness: 0.095 +/- 0.008
6. FMS tolerances: 4/- 0.003 unless specified otherwise
7. Zc=50 Ohm, Zd=100 Ohm Controlled Impedance
8. Apply Solder Mask over bare copper.
9. Do not increase size of thermal pads on holes.
10. Remove all non-functional inner layer pads for pins and vias.
11. Do not increase size of thermal pads and associated spoke connections on holes.